Materials Declaration

Package	CSP BGA
Body Size	13 X 13
Ball Count	108
Option	SnAgCu

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87	1.71 E-01	268304
Biphenyl Resin	13	2.56 E-02	40167
Sb2O3	0.5	1.00 E-03	1569
Brominated Compound	0.3	6.00 E-04	941
		1.98 E-01	**310982**

Molding Compound

Item	PPM	Method
Pb	8.20	US EPA Method #3052
Cd	Not Detected	US EPA Method #3052
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	46.5	1.22 E-01	191108
Solder Mask	6.2	1.63 E-02	25575
Copper	41.2	1.08 E-01	169612
Gold	0.4	1.10 E-03	1726
Nickel	2.5	6.50 E-03	10199
Brominated Compound	3.2	8.30 E-03	13023
		2.62 E-01	**411243**

Solder Ball

	% of Solder Ball	Weight (g)	PPM
Sn	96.5	1.10 E-01	172280
Ag	3.0	3.40 E-03	5335
Cu	0.5	6.00 E-04	941
		1.14 E-01	**178556**

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	7.44 E-03	11667

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.92 E-02	77196

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25.0	1.60 E-03	2510
Ag Filler	75.0	5.00 E-03	7845
		6.60 E-03	**10356**

Package Totals

Weight (g)	PPM
6.37E-01	1000000

AMK-BC-E

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ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

2/17/06

Materials Declaration

Package	CSP BGA
Body Size	13 X 13
Ball Count	108
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87	1.71 E-01	259628
Biphenyl Resin	13	2.56 E-02	38868
Sb2O3	0.5	1.00 E-03	1518
Brominated Compound	0.3	6.00 E-04	911
		1.98 E-01	**300925**

Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	46.5	1.22 E-01	184928
Solder Mask	6.2	1.63 E-02	24748
Copper	41.2	1.08 E-01	164127
Gold	0.4	1.10 E-03	1670
Nickel	2.5	6.50 E-03	9869
Brominated Compound	3.2	8.30 E-03	12602
		2.62 E-01	**397944**

Solder Ball

	% of Solder Ball	Weight (g)	PPM
Sn	63.0	8.51 E-02	129206
Pb	37.0	5.00 E-02	75914
		1.35 E-01	**205121**

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	7.44 E-03	11290

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.92 E-02	74700

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25.0	1.60 E-03	2429
Ag Filler	75.0	5.00 E-03	7591
		6.60 E-03	**10021**

Package Totals

Weight (g)	PPM
6.59E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA Method #3050B
Cd	Not Detected	BS EN 1122:2001, Method B
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

AMK-BC-B

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ANALOG DEVICES

ADI Proprietary

2/17/06